

CURRENT LEAD FREE SERIAL EEPROMS OFFERED BY ISSI



Q: How do we differentiate Lead Free Product from Non-Lead Free Product?

A: The package code for Lead Free is different from a Non Lead Free Product. For example, a Non-Lead Free 8-pin SOIC has a package designator of 'G' and the Lead Free 8-pin SOIC has a package designator of 'GL'. We simply added a 'L' to the old package code.

Q: Is it RoHS Compliant?

RoHS - European Union's Restriction on Hazardous Substances Directive (which bans the industry's use of lead, mercury, cadmium, hexavalent chromium and two brominated flame retardants –PBB and PBDE).

A: Yes

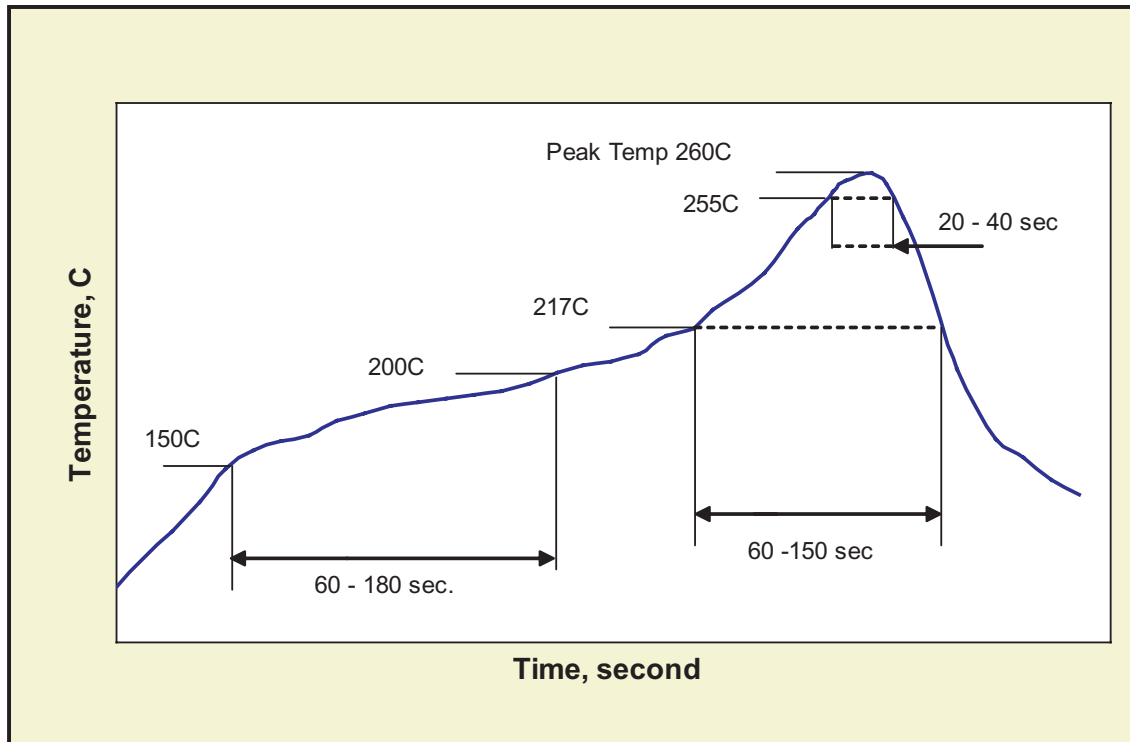
Q: What is the plating for lead frame finger?

A: 100% Matte Tin

Q: What devices are available in Lead Free packaging?

A: ISSI is offering Lead Free for all its devices with densities from 1Kbit to 128Kbit and with bus protocols Microwire, I²C™, and SPI.

IR Reflow Temperature Profile (Pb-Free)



ISSI Spec

Average ramp-up rate	< 3°C/sec
Preheat temperature 150°C to 200°C	60 – 180 sec
Temperature maintained above 217°C	60 – 150 sec
Peak temperature	260°C
Temperature > 255°C	20 – 40 sec
Ramp-down rate	< 6°C/sec